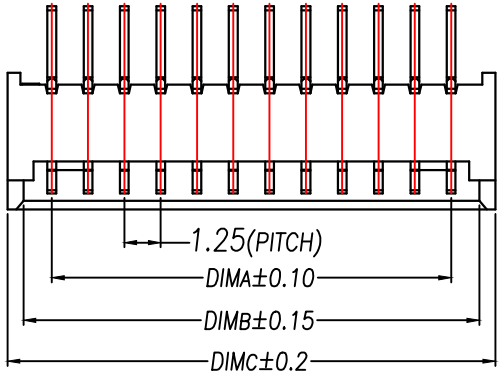
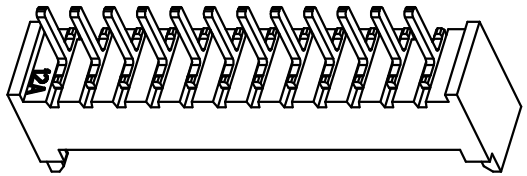
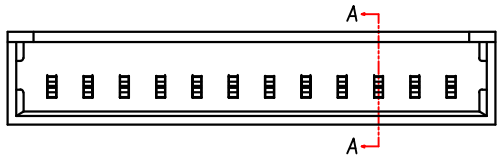
REV.	DESCRIPTION	ECN NO.	NAME	DATE

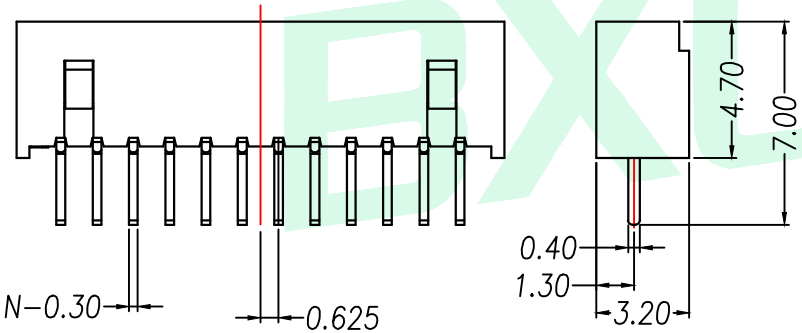
PRELIMINARY
DESIGN IS SUBJECT TO CHANGE WITHOUT PRIOR NOTICE

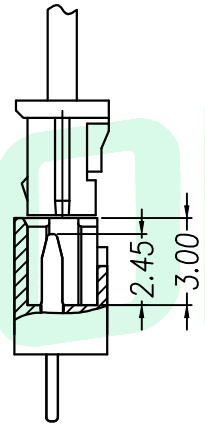




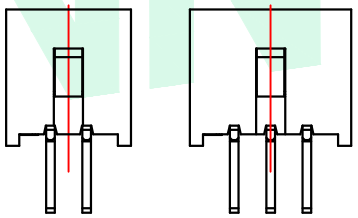
NOTES:
1. Working temp:−25°C~85°C.
2. Voltage rating:125V AC/DC(rms)
3. Contact resistance:55mΩ max.
4. Insulation resistance:100MΩ min.
5. Current rating:1A AV/DC
6. Withstanding Voltage:500V AC/minute
7. Pin Retention Force:5N min.
8. Housing material:LCP UL94−V0,Natural
9. Terminal materl:Brass,
   plating Ni 40u" min , plating Tin 100u"min.
10. Solder tab material:Brass,
   plating Ni 40u" min , plating Tin 100u"min.





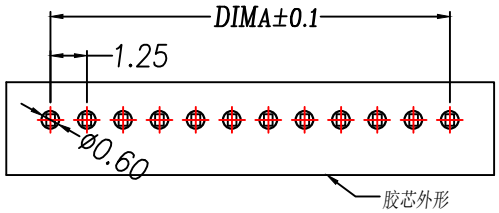


SECTION A−A



LOCK CONFIGURATION (锁扣位置)

PIN	No.	Dim A	Dim B	Dim C
1	WF-MX1.25-2PZZ	1.25	3.20	4.30
2	WF-MX1.25-3PZZ	2.50	4.45	5.55
3	WF-MX1.25-4PZZ	3.75	5.70	6.80
4	WF-MX1.25-5PZZ	5.00	6.95	8.05
5	WF-MX1.25-6PZZ	6.25	8.20	9.30
6	WF-MX1.25-7PZZ	7.50	9.45	10.55
7	WF-MX1.25-8PZZ	8.75	10.70	11.80
8	WF-MX1.25-9PZZ	10.00	11.95	13.05
9	WF-MX1.25-10PZZ	11.25	13.20	14.30
10	WF-MX1.25-11PZZ	12.50	14.45	15.55
11	WF-MX1.25-12PZZ	13.75	15.70	16.80
12	WF-MX1.25-13PZZ	15.00	16.95	18.05
13	WF-MX1.25-14PZZ	16.25	18.20	19.30
14	WF-MX1.25-15PZZ	17.50	19.45	20.55
15	WF-MX1.25-16PZZ	18.75	20.70	21.80



RECOMMENDED PCB LAYOUT TOP VIEW (TOLERANCE:±0.05)

GENERAL TOLERANCE					
DIM.	TOL.				
X					
X.X	±0.30				
X.XX	±0.25				
X.XXX	±0.15				
GENERAL ANGLE:	±3°				
DONGGUAN BAOXUN PRECISION TECHNOLOGY CO., LTD					
TITLE: WAFER 1.25mm H4.7mm 180°DIP					
DWG. NO.: WF−MX1.25−XPZZ				DRAWN: MAX	
PART NO.: WF−MX1.25−XPZZ				CHECKED: ELLA	
UNIT: mm	SCALE: none	SHEET: 1of 1	DWG. SIZE: A4	LAYER: bxconn	APPROVED: WILL

BXCONN®